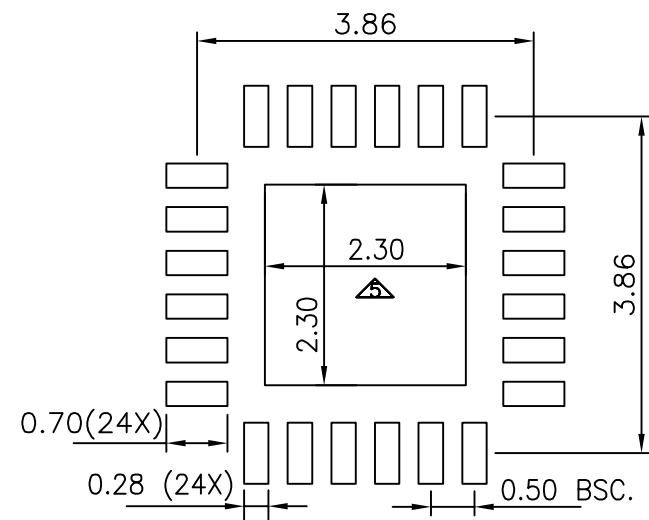
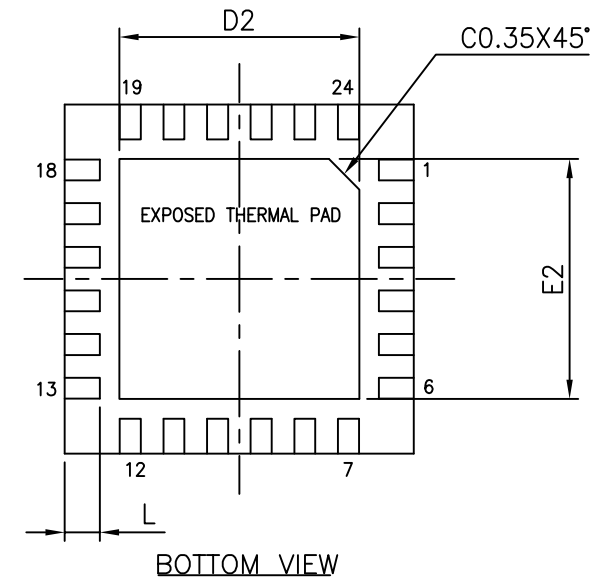
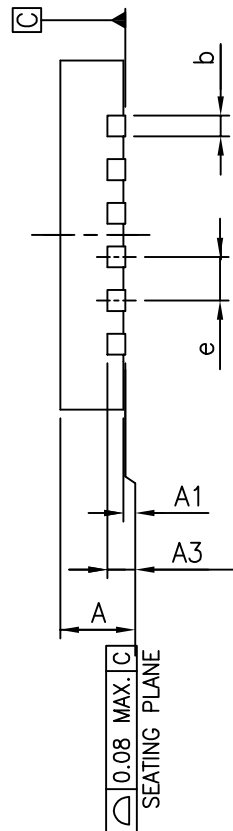


SYMBOLS	MIN.	NOM.	MAX.
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
A3	0.20 REF.		
b	0.18	0.25	0.30
D	3.90	4.00	4.10
E	3.90	4.00	4.10
e	0.50 BSC		
D2	2.15	—	2.75
E2	2.15	—	2.75
L	0.35	0.40	0.45



NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-220
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA
6. MAJOR EDAP D2XE2=2.25X2.25

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DATE: 07/07/17

DESCRIPTION: 24-Contact, Very Thin Quad Flat No-Lead (TQFN)

PACKAGE CODE: ZD (ZD24)

DOCUMENT CONTROL #: PD-2100

REVISION: C